

Serial Nr.: 09/627,979 Art Unit: 2814

JAN-04-2003 13:43 FROM: JASON Z LIN

UPA-00156

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.:

09/627,979

Examiner: DiLinh Nguyen

Inventor:

Randy H. Y. Lo, Chi-Chuan Wu and Ssu-Cheng Lai June 24, 2000

Art Unit:

Filed: Title:

Method Of Packaging Multi Chip Module

Certificate of Transmission under 37 CFR 1.8

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Commissioner for Patents Washington, D.C. 20231

Sir:

AMENDMENT C

In response to the Office Action mailed 11/20/2002, please amend the aboveidentified application as follows:

SPECIFICATION:

Page 6, between lines 6 and 7, insert the following paragraph:

The present invention presents an MCM package structure in which at least one CSP is packaged along with another CSP or a bare die. In other words, there are two levels of packaged structures in the MCM package. The conventional CSP forms the first level of the packaged structure and the MCM forms the second level of the packaged structure. As shown in FIG. 2A, a conventional CSP 221 has a bare die 22 embedded and disposed above a CSP substrate 21, wires 25 for connecting the bare die 22 to the